

Amendment and Response

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Title: MULTICHIP PACKAGE WITH CLOCK FREQUENCY ADJUSTMENT

IN THE ABSTRACT

Please replace the Abstract with the following rewritten Abstract:

One embodiment of the present invention provides a multi-chip package including a logic device providing a clock signal having a frequency and a memory device. The memory device receives the clock signal and operates at the clock signal frequency. The memory device includes a temperature sensor providing a temperature signal indicative of a temperature of the memory device, wherein the logic device adjusts the clock signal frequency ~~bases~~based on the temperature signal.